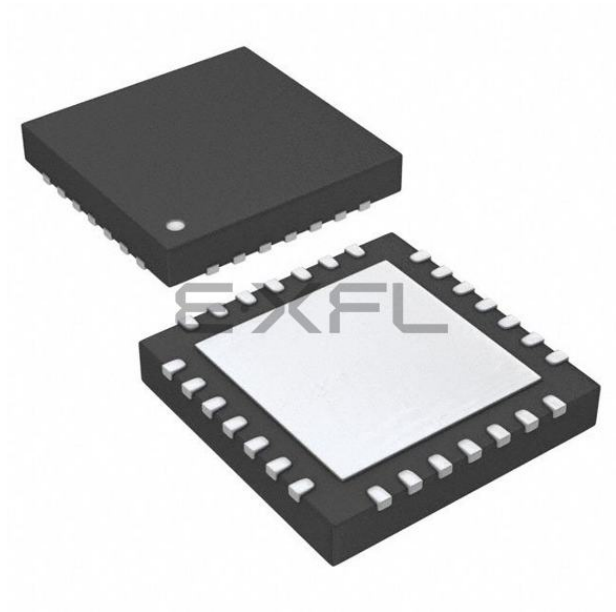

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PSMC, PWM, WDT
Number of I/O	24
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 11x12b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UFQFN Exposed Pad
Supplier Device Package	28-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1783-e-mv

3.1.1 READING PROGRAM MEMORY AS DATA

There are two methods of accessing constants in program memory. The first method is to use tables of RETLW instructions. The second method is to set an FSR to point to the program memory.

3.1.1.1 RETLW Instruction

The RETLW instruction can be used to provide access to tables of constants. The recommended way to create such a table is shown in Example 3-1.

EXAMPLE 3-1: RETLW INSTRUCTION

```
constants
    BRW                 ;Add Index in W to
                        ;program counter to
                        ;select data
    RETLW DATA0         ;Index0 data
    RETLW DATA1         ;Index1 data
    RETLW DATA2
    RETLW DATA3


my_function
    ;… LOTS OF CODE…
    MOVLW       DATA_INDEX
    call constants
    ;… THE CONSTANT IS IN W
```

The BRW instruction makes this type of table very simple to implement. If your code must remain portable with previous generations of microcontrollers, then the BRW instruction is not available so the older table read method must be used.

3.1.1.2 Indirect Read with FSR

The program memory can be accessed as data by setting bit 7 of the FSRxH register and reading the matching INDFx register. The MOVIW instruction will place the lower 8 bits of the addressed word in the W register. Writes to the program memory cannot be performed via the INDF registers. Instructions that access the program memory via the FSR require one extra instruction cycle to complete. Example 3-2 demonstrates accessing the program memory via an FSR.

The high directive will set bit<7> if a label points to a location in program memory.

EXAMPLE 3-2: ACCESSING PROGRAM MEMORY VIA FSR

```
constants
    RETLW DATA0         ;Index0 data
    RETLW DATA1         ;Index1 data
    RETLW DATA2
    RETLW DATA3
my_function
    ;… LOTS OF CODE…
    MOVLW   LOW constants
    MOVWF   FSR1L
    MOVLW   HIGH constants
    MOVWF   FSR1H
    MOVIW   0[FSR1]
;THE PROGRAM MEMORY IS IN W
```

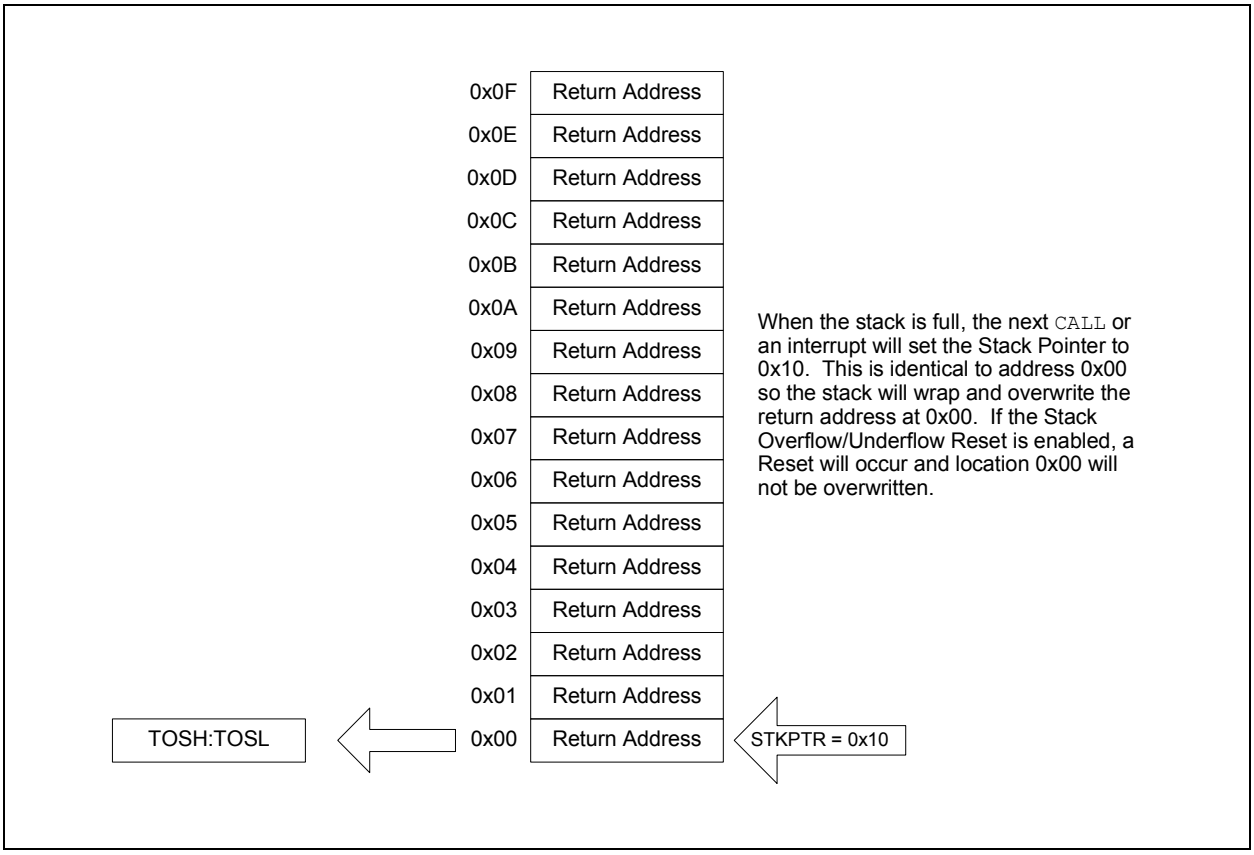
TABLE 3-8: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 16											
80Ch — 810h	—	Unimplemented								—	—
811h	PSMC1CON	PSMC1EN	PSMC1LD	PSMC1DBFE	PSMC1DBRE	P1MODE<3:0>				0000 0000	0000 0000
812h	PSMC1MDL	P1MDLEN	P1MDLPOL	P1MDLBIT	—	P1MSRC<3:0>				000- 0000	000- 0000
813h	PSMC1SYNC	—	—	—	—	—	—	P1SYNC<1:0>		---- --00	---- --00
814h	PSMC1CLK	—	—	P1CPRE<1:0>		—	—	P1CSRC<1:0>		--00 --00	--00 --00
815h	PSMC1OEN	—	—	P1OEF	P1OEE	P1OED	P1OEC	P1OEB	P1OEA	--00 0000	--00 0000
816h	PSMC1POL	—	P1INPOL	P1POLF	P1POLE	P1POLD	P1POLC	P1POLB	P1POLA	-000 0000	-000 0000
817h	PSMC1BLNK	—	—	P1FEBM<1:0>		—	—	P1REBM<1:0>		--00 --00	--00 --00
818h	PSMC1REBS	P1REBIN	—	—	—	P1REBSC3	P1REBSC2	P1REBSC1	—	0--- 000-	0--- 000-
819h	PSMC1FEBS	P1FEBIN	—	—	—	P1FEBSC3	P1FEBSC2	P1FEBSC1	—	0--- 000-	0--- 000-
81Ah	PSMC1PHS	P1PHSIN	—	—	—	P1PHSC3	P1PHSC2	P1PHSC1	P1PHST	0--- 0000	0--- 0000
81Bh	PSMC1DCS	P1DCSIN	—	—	—	P1DCSC3	P1DCSC2	P1DCSC1	P1DCST	0--- 0000	0--- 0000
81Ch	PSMC1PRS	P1PRSIN	—	—	—	P1PRSC3	P1PRSC2	P1PRSC1	P1PRST	0--- 0000	0--- 0000
81Dh	PSMC1ASDC	P1ASE	P1ASDEN	P1ARSEN	—	—	—	—	P1ASDOV	000- ---0	000- ---0
81Eh	PSMC1ASDL	—	—	P1ASDLF	P1ASDLE	P1ASDLD	P1ASDLC	P1ASDLB	P1ASDLA	--00 0000	--00 0000
81Fh	PSMC1ASDS	P1ASDSIN	—	—	—	P1ASDSC3	P1ASDSC2	P1ASDSC1	—	0--- 000-	0--- 000-
820h	PSMC1INT	P1TOVIE	P1TPHIE	P1TDCIE	P1TPRIE	P1TOVIF	P1TPHIF	P1TDCIF	P1TPRIF	0000 0000	0000 0000
821h	PSMC1PHL	Phase Low Count								0000 0000	0000 0000
822h	PSMC1PHH	Phase High Count								0000 0000	0000 0000
823h	PSMC1DCL	Duty Cycle Low Count								0000 0000	0000 0000
824h	PSMC1DCH	Duty Cycle High Count								0000 0000	0000 0000
825h	PSMC1PRL	Period Low Count								0000 0000	0000 0000
826h	PSMC1PRH	Period High Count								0000 0000	0000 0000
827h	PSMC1TMRL	Time base Low Counter								0000 0001	0000 0001
828h	PSMC1TMRH	Time base High Counter								0000 0000	0000 0000
829h	PSMC1DBR	rising Edge Dead-band Counter								0000 0000	0000 0000
82Ah	PSMC1DBF	Falling Edge Dead-band Counter								0000 0000	0000 0000
82Bh	PSMC1BLKR	rising Edge Blanking Counter								0000 0000	0000 0000
82Ch	PSMC1BLKF	Falling Edge Blanking Counter								0000 0000	0000 0000
82Dh	PSMC1FFA	—	—	—	—	Fractional Frequency Adjust Register				---- 0000	---- 0000
82Eh	PSMC1STR0	—	—	P1STRF	P1STRE	P1STRD	P1STRC	P1STRB	P1STRA	--00 0001	--00 0001
82Fh	PSMC1STR1	P1SYNC	—	—	—	—	—	P1LSMEN	P1HSMEN	0--- --00	0--- --00
830h	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved.
Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.
2: Unimplemented, read as '1'.
3: PIC16F1782/3 only.

FIGURE 3-8: ACCESSING THE STACK EXAMPLE 4



3.5.2 OVERFLOW/UNDERFLOW RESET

If the STVREN bit in Configuration Words is programmed to '1', the device will be reset if the stack is PUSHed beyond the sixteenth level or POPed beyond the first level, setting the appropriate bits (STKOVF or STKUNF, respectively) in the PCON register.

3.6 Indirect Addressing

The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the File Select Registers (FSR). If the FSRn address specifies one of the two INDFn registers, the read will return '0' and the write will not occur (though Status bits may be affected). The FSRn register value is created by the pair FSRnH and FSRnL.

The FSR registers form a 16-bit address that allows an addressing space with 65536 locations. These locations are divided into three memory regions:

- Traditional Data Memory
- Linear Data Memory
- Program Flash Memory

6.6 Register Definitions: Oscillator Control

REGISTER 6-1: OSCCON: OSCILLATOR CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-1/1	R/W-1/1	R/W-1/1	U-0	R/W-0/0	R/W-0/0
SPLLEN	IRCF<3:0>				—	SCS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **SPLLEN:** Software PLL Enable bit
If PLLEN in Configuration Words = 1:
SPLLEN bit is ignored. 4x PLL is always enabled (subject to oscillator requirements)
If PLLEN in Configuration Words = 0:
1 = 4x PLL Is enabled
0 = 4x PLL is disabled

bit 6-3 **IRCF<3:0>:** Internal Oscillator Frequency Select bits
1111 = 16 MHz HF or 32 MHz HF(2)
1110 = 8 MHz or 32 MHz HF(2)
1101 = 4 MHz HF
1100 = 2 MHz HF
1011 = 1 MHz HF
1010 = 500 kHz HF(1)
1001 = 250 kHz HF(1)
1000 = 125 kHz HF(1)
0111 = 500 kHz MF (default upon Reset)
0110 = 250 kHz MF
0101 = 125 kHz MF
0100 = 62.5 kHz MF
0011 = 31.25 kHz HF(1)
0010 = 31.25 kHz MF
000x = 31 kHz LF

bit 2 **Unimplemented:** Read as ‘0’

bit 1-0 **SCS<1:0>:** System Clock Select bits
1x = Internal oscillator block
01 = Timer1 oscillator
00 = Clock determined by FOSC<2:0> in Configuration Words.

Note 1: Duplicate frequency derived from HFINTOSC.
2: 32 MHz when SPLLEN bit is set. Refer to **Section 6.2.2.6 “32 MHz Internal Oscillator Frequency Selection”**.

REGISTER 8-4: PIE4: PERIPHERAL INTERRUPT ENABLE REGISTER 4

U-0	U-0	R/W-0/0	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0
—	—	PSMC2TIE	PSMC1TIE	—	—	PSMC2SIE	PSMC1SIE
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5 **PSMC2TIE:** PSMC2 Time Base Interrupt Enable bit
- 1 = Enables PSMC2 time base generated interrupts
- 0 = Disables PSMC2 time base generated interrupts

bit 4 **PSMC1TIE:** PSMC1 Time Base Interrupt Enable bit
- 1 = Enables PSMC1 time base generated interrupts
- 0 = Disables PSMC1 time base generated interrupts

bit 3-2 **Unimplemented:** Read as '0'

bit 1 **PSMC2SIE:** PSMC2 Auto-Shutdown Interrupt Enable bit
- 1 = Enables PSMC2 auto-shutdown interrupts
- 0 = Disables PSMC2 auto-shutdown interrupts

bit 0 **PSMC1SIE:** PSMC1 Auto-Shutdown Interrupt Enable bit
- 1 = Enables PSMC1 auto-shutdown interrupts
- 0 = Disables PSMC1 auto-shutdown interrupts

Note: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt.

9.0 POWER-DOWN MODE (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{PD}$ bit of the STATUS register is cleared.
3. $\overline{TO}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Timer1 and peripherals that operate from Timer1 continue operation in Sleep when the Timer1 clock source selected is:
   - LFINTOSC
   - T1CKI
   - Timer1 oscillator
7. ADC is unaffected, if the dedicated FRC oscillator is selected.
8. I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).
9. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- Modules using Timer1 oscillator

I/O pins that are high-impedance inputs should be pulled to VDD or VSS externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include modules such as the DAC and FVR modules. See **Section 19.0 "Digital-to-Analog Converter (DAC) Module"** and **Section 15.0 "Fixed Voltage Reference (FVR)"** for more information on these modules.

9.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

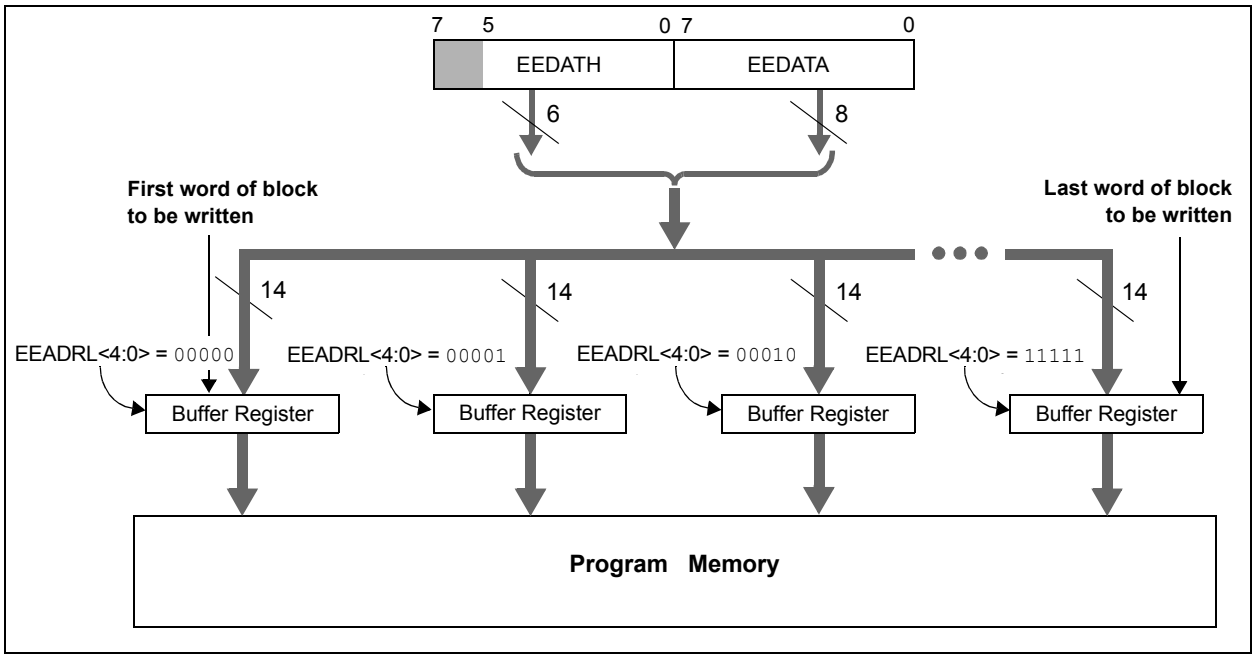
1. External Reset input on $\overline{MCLR}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 5.12 "Determining the Cause of a Reset"**.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is enabled, the device executes the instruction after the SLEEP instruction, the device will then call the Interrupt Service Routine. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

FIGURE 12-2: BLOCK WRITES TO FLASH PROGRAM MEMORY WITH 32 WRITE LATCHES



EXAMPLE 12-4: ERASING ONE ROW OF PROGRAM MEMORY

```
; This row erase routine assumes the following:
; 1. A valid address within the erase block is loaded in ADDRH:ADDRL
; 2. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F (common RAM)


        BCF         INTCON,GIE      ; Disable ints so required sequences will execute properly
        BANKSEL     EEADRL
        MOVF        ADDRL,W         ; Load lower 8 bits of erase address boundary
        MOVWF       EEADRL
        MOVF        ADDRH,W         ; Load upper 6 bits of erase address boundary
        MOVWF       EEADRH
        BSF         EECON1,EEPGD    ; Point to program memory
        BCF         EECON1,CFGS     ; Not configuration space
        BSF         EECON1,FREE     ; Specify an erase operation
        BSF         EECON1,WREN     ; Enable writes

Required
Sequence
        MOVLW       55h             ; Start of required sequence to initiate erase
        MOVWF       EECON2          ; Write 55h
        MOVLW       0AAh            ;
        MOVWF       EECON2          ; Write AAh
        BSF         EECON1,WR       ; Set WR bit to begin erase
        NOP                         ; Any instructions here are ignored as processor
                                    ; halts to begin erase sequence
        NOP                         ; Processor will stop here and wait for erase complete.

                                    ; after erase processor continues with 3rd instruction

        BCF         EECON1,WREN     ; Disable writes
        BSF         INTCON,GIE      ; Enable interrupts
```

REGISTER 13-21: WPUC: WEAK PULL-UP PORTC REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
WPUC7	WPUC6	WPUC5	WPUC4	WPUC3	WPUC2	WPUC1	WPUC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **WPUC<7:0>**: Weak Pull-up Register bits
1 = Pull-up enabled
0 = Pull-up disabled

Note 1: Global $\overline{\text{WPUEN}}$ bit of the OPTION_REG register must be cleared for individual pull-ups to be enabled.
2: The weak pull-up device is automatically disabled if the pin is in configured as an output.

REGISTER 13-22: ODCONC: PORTC OPEN DRAIN CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
ODC7	ODC6	ODC5	ODC4	ODC3	ODC2	ODC1	ODC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **ODC<7:0>:** PORTC Open Drain Enable bits
For RC<7:0> pins, respectively
1 = Port pin operates as open-drain drive (sink current only)
0 = Port pin operates as standard push-pull drive (source and sink current)

REGISTER 13-23: SLRCONC: PORTC SLEW RATE CONTROL REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
SLRC7	SLRC6	SLRC5	SLRC4	SLRC3	SLRC2	SLRC1	SLRC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **SLRC<7:0>:** PORTC Slew Rate Enable bits
For RC<7:0> pins, respectively
1 = Port pin slew rate is limited
0 = Port pin slews at maximum rate

20.10 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 20-4. Since the analog input pins share their connection with a digital input, they have reverse biased ESD protection diodes to VDD and VSS. The analog input, therefore, must be between VSS and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur.

A maximum source impedance of 10 kΩ is recommended for the analog sources. Also, any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current to minimize inaccuracies introduced.

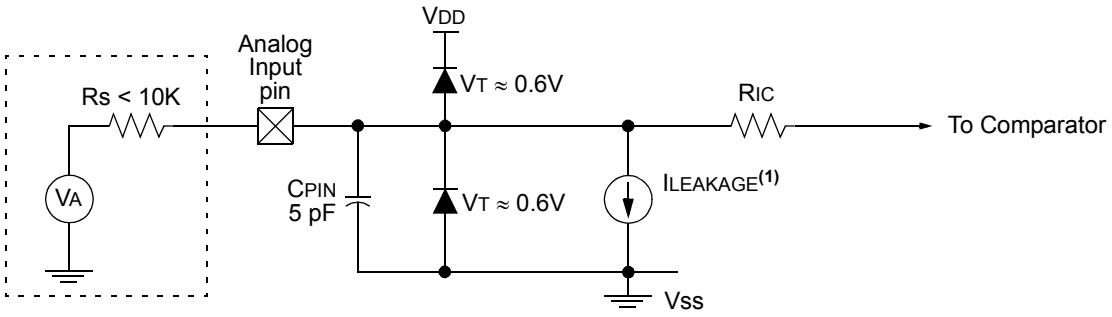
Note 1: When reading a PORT register, all pins configured as analog inputs will read as a '0'. Pins configured as digital inputs will convert as an analog input, according to the input specification.

2: Analog levels on any pin defined as a digital input, may cause the input buffer to consume more current than is specified.

20.10.1 ALTERNATE PIN LOCATIONS

This module incorporates I/O pins that can be moved to other locations with the use of the alternate pin function register APFCON. To determine which pins can be moved and what their default locations are upon a Reset, see **Section 13.1 "Alternate Pin Function"** for more information.

FIGURE 20-4: ANALOG INPUT MODEL



Legend: CPIN = Input Capacitance
ILEAKAGE = Leakage Current at the pin due to various junctions
RIC = Interconnect Resistance
RS = Source Impedance
VA = Analog Voltage
VT = Threshold Voltage

Note 1: See **Section 30.0 "Electrical Specifications"**

FIGURE 22-3: TIMER1 GATE ENABLE MODE

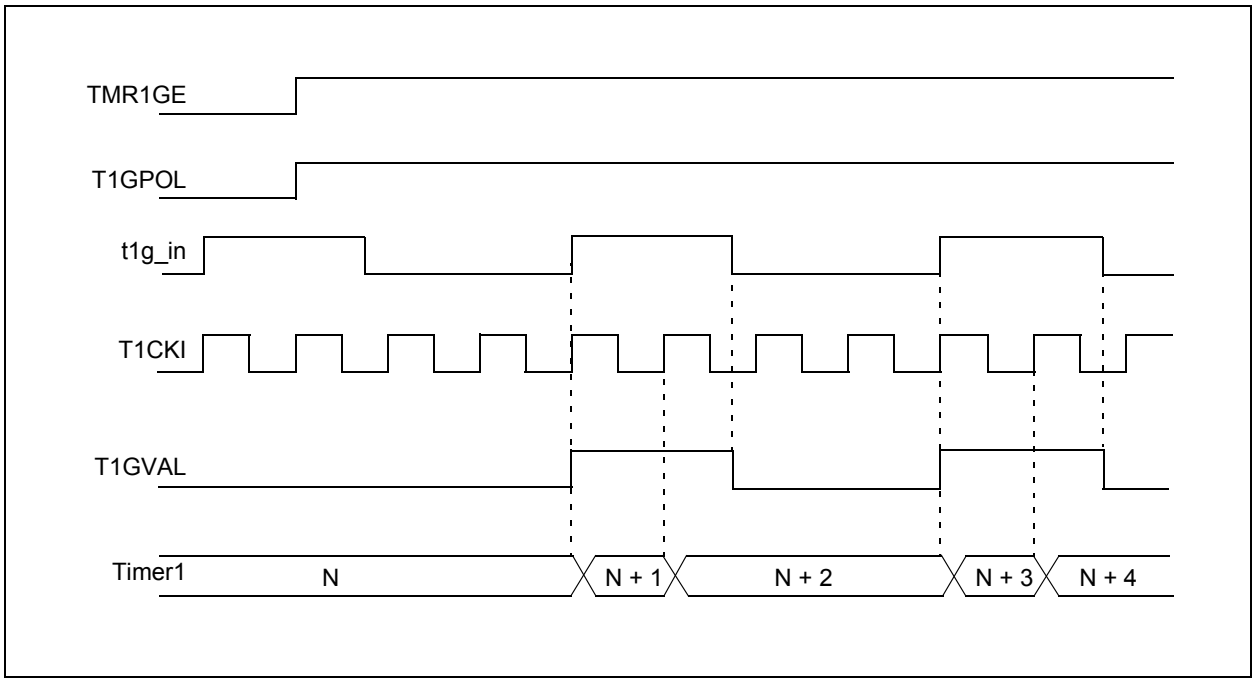


FIGURE 22-4: TIMER1 GATE TOGGLE MODE

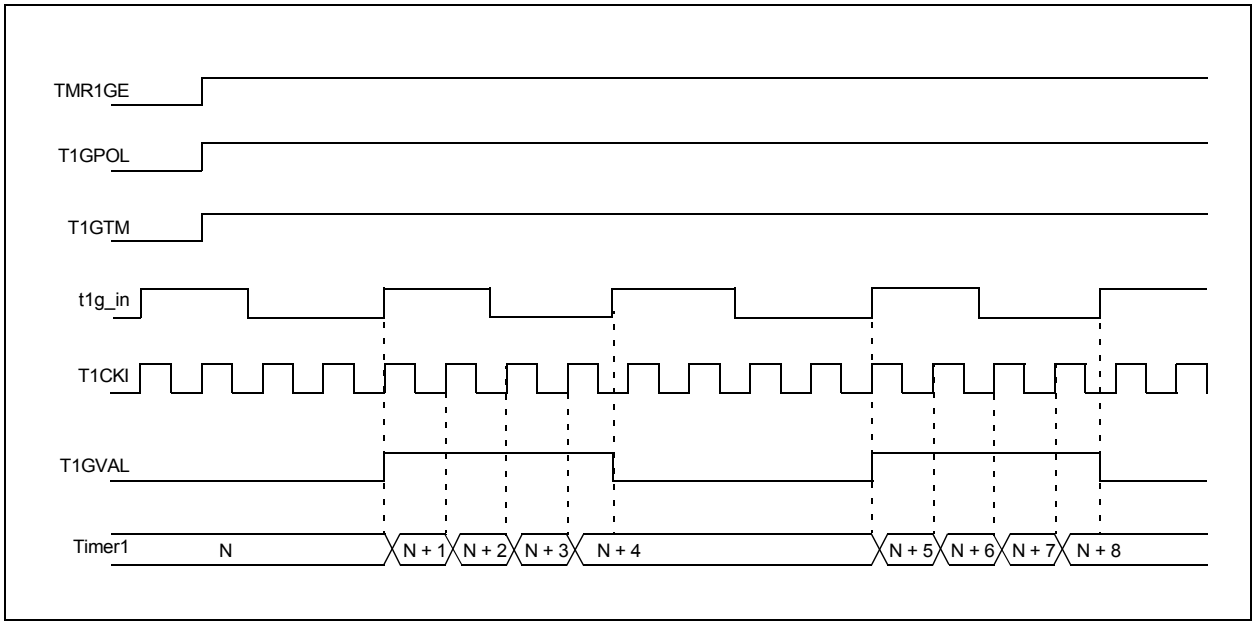
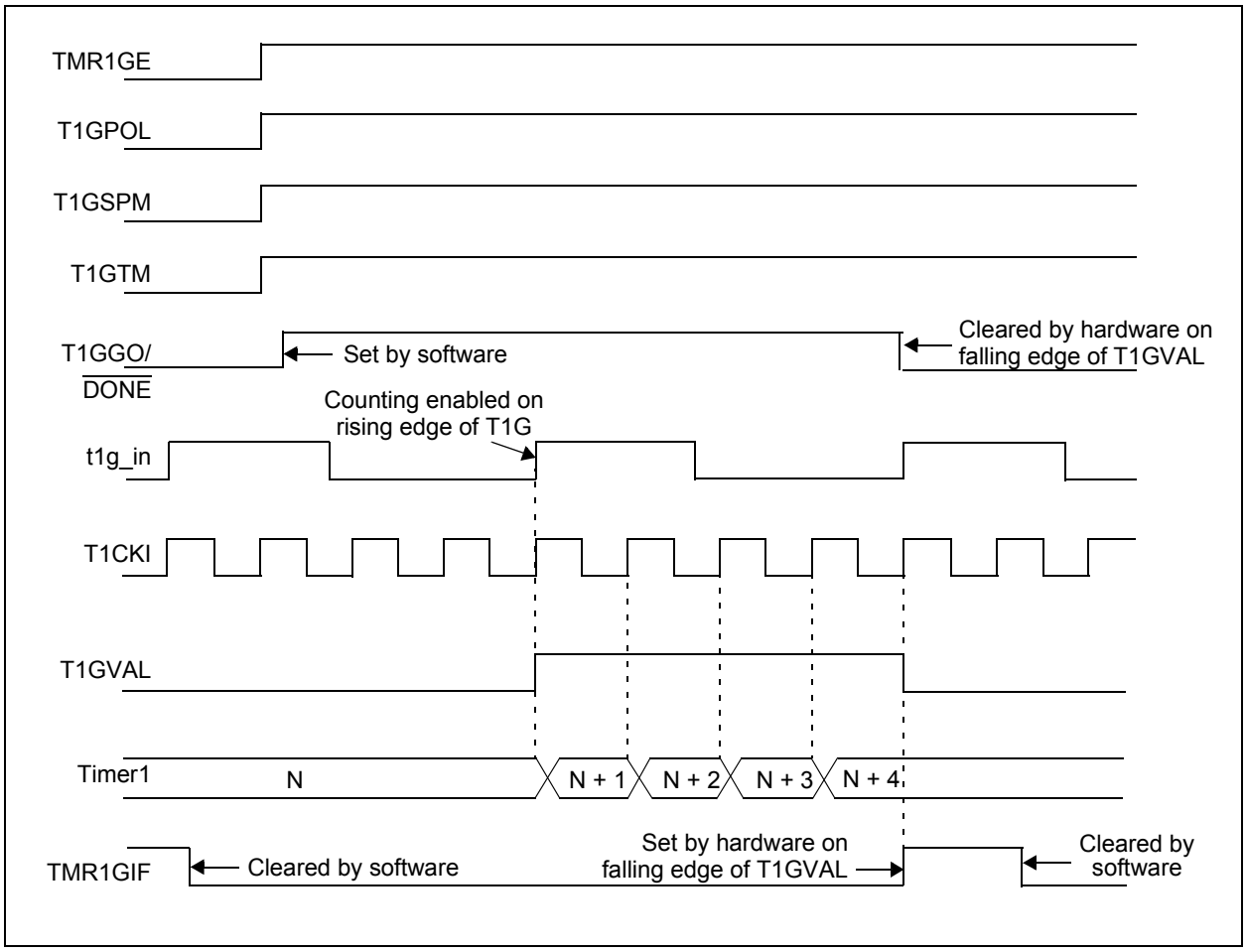


FIGURE 22-6: TIMER1 GATE SINGLE-PULSE AND TOGGLE COMBINED MODE



26.6 I²C Master Mode

Master mode is enabled by setting and clearing the appropriate SSPM bits in the SSPCON1 register and by setting the SSPEN bit. In Master mode, the SDA and SCK pins must be configured as inputs. The MSSP peripheral hardware will override the output driver TRIS controls when necessary to drive the pins low.

Master mode of operation is supported by interrupt generation on the detection of the Start and Stop conditions. The Stop (P) and Start (S) bits are cleared from a Reset or when the MSSP module is disabled. Control of the I²C bus may be taken when the P bit is set, or the bus is Idle.

In Firmware Controlled Master mode, user code conducts all I²C bus operations based on Start and Stop bit condition detection. Start and Stop condition detection is the only active circuitry in this mode. All other communication is done by the user software directly manipulating the SDA and SCL lines.

The following events will cause the SSP Interrupt Flag bit, SSP1IF, to be set (SSP interrupt, if enabled):

- Start condition detected
- Stop condition detected
- Data transfer byte transmitted/received
- Acknowledge transmitted/received
- Repeated Start generated

Note 1: The MSSP module, when configured in I²C Master mode, does not allow queueing of events. For instance, the user is not allowed to initiate a Start condition and immediately write the SSPBUF register to initiate transmission before the Start condition is complete. In this case, the SSPBUF will not be written to and the WCOL bit will be set, indicating that a write to the SSPBUF did not occur

2: When in Master mode, Start/Stop detection is masked and an interrupt is generated when the SEN/PEN bit is cleared and the generation is complete.

26.6.1 I²C MASTER MODE OPERATION

The master device generates all of the serial clock pulses and the Start and Stop conditions. A transfer is ended with a Stop condition or with a Repeated Start condition. Since the Repeated Start condition is also the beginning of the next serial transfer, the I²C bus will not be released.

In Master Transmitter mode, serial data is output through SDA, while SCL outputs the serial clock. The first byte transmitted contains the slave address of the receiving device (7 bits) and the Read/Write (R/$\overline{W}$) bit. In this case, the R/$\overline{W}$ bit will be logic '0'. Serial data is transmitted 8 bits at a time. After each byte is transmitted, an Acknowledge bit is received. Start and Stop conditions are output to indicate the beginning and the end of a serial transfer.

In Master Receive mode, the first byte transmitted contains the slave address of the transmitting device (7 bits) and the R/$\overline{W}$ bit. In this case, the R/$\overline{W}$ bit will be logic '1'. Thus, the first byte transmitted is a 7-bit slave address followed by a '1' to indicate the receive bit. Serial data is received via SDA, while SCL outputs the serial clock. Serial data is received 8 bits at a time. After each byte is received, an Acknowledge bit is transmitted. Start and Stop conditions indicate the beginning and end of transmission.

A Baud Rate Generator is used to set the clock frequency output on SCL. See **Section 26.7 "Baud Rate Generator"** for more detail.

27.1.1.5 TSR Status

The TRMT bit of the TXSTA register indicates the status of the TSR register. This is a read-only bit. The TRMT bit is set when the TSR register is empty and is cleared when a character is transferred to the TSR register from the TXREG. The TRMT bit remains clear until all bits have been shifted out of the TSR register. No interrupt logic is tied to this bit, so the user has to poll this bit to determine the TSR status.

Note:	The TSR register is not mapped in data memory, so it is not available to the user.

27.1.1.6 Transmitting 9-Bit Characters

The EUSART supports 9-bit character transmissions. When the TX9 bit of the TXSTA register is set, the EUSART will shift 9 bits out for each character transmitted. The TX9D bit of the TXSTA register is the ninth, and Most Significant, data bit. When transmitting 9-bit data, the TX9D data bit must be written before writing the eight Least Significant bits into the TXREG. All 9 bits of data will be transferred to the TSR shift register immediately after the TXREG is written.

A special 9-bit Address mode is available for use with multiple receivers. See **Section 27.1.2.7 "Address Detection"** for more information on the address mode.

27.1.1.7 Asynchronous Transmission Set-up:

1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 27.4 "EUSART Baud Rate Generator (BRG)"**).
2. Enable the asynchronous serial port by clearing the SYNC bit and setting the SPEN bit.
3. If 9-bit transmission is desired, set the TX9 control bit. A set ninth data bit will indicate that the 8 Least Significant data bits are an address when the receiver is set for address detection.
4. Set SCKP bit if inverted transmit is desired.
5. Enable the transmission by setting the TXEN control bit. This will cause the TXIF interrupt bit to be set.
6. If interrupts are desired, set the TXIE interrupt enable bit of the PIE1 register. An interrupt will occur immediately provided that the GIE and PEIE bits of the INTCON register are also set.
7. If 9-bit transmission is selected, the ninth bit should be loaded into the TX9D data bit.
8. Load 8-bit data into the TXREG register. This will start the transmission.

FIGURE 27-3: ASYNCHRONOUS TRANSMISSION

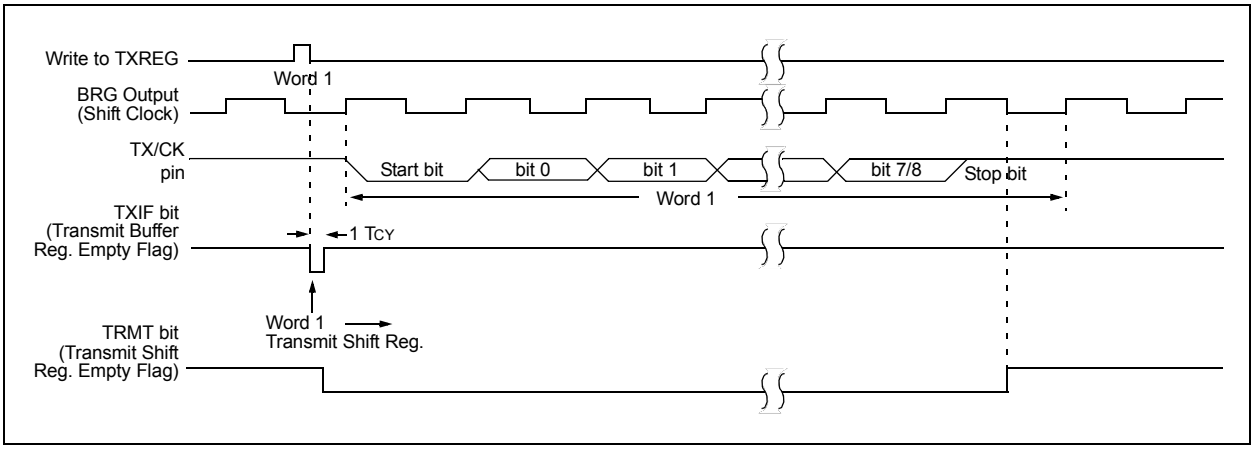


TABLE 29-3: INSTRUCTION SET (CONTINUED)

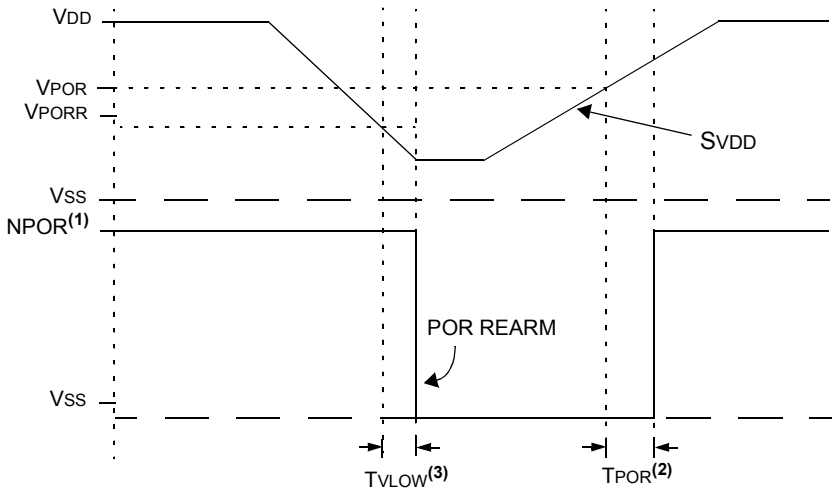
Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb LSb	Status Affected	Notes
CONTROL OPERATIONS						
BRA	k	Relative Branch	2	11 001k kkkk kkkk		
BRW	–	Relative Branch with W	2	00 0000 0000 1011		
CALL	k	Call Subroutine	2	10 0kkk kkkk kkkk		
CALLW	–	Call Subroutine with W	2	00 0000 0000 1010		
GOTO	k	Go to address	2	10 1kkk kkkk kkkk		
RETFIE	k	Return from interrupt	2	00 0000 0000 1001		
RETLW	k	Return with literal in W	2	11 0100 kkkk kkkk		
RETURN	–	Return from Subroutine	2	00 0000 0000 1000		
INHERENT OPERATIONS						
CLRWDT	–	Clear Watchdog Timer	1	00 0000 0110 0100	$\overline{TO}$, $\overline{PD}$	
NOP	–	No Operation	1	00 0000 0000 0000		
OPTION	–	Load OPTION_REG register with W	1	00 0000 0110 0010		
RESET	–	Software device Reset	1	00 0000 0000 0001		
SLEEP	–	Go into Standby mode	1	00 0000 0110 0011	$\overline{TO}$, $\overline{PD}$	
TRIS	f	Load TRIS register with W	1	00 0000 0110 0fff		
C-COMPILER OPTIMIZED						
ADDFSR	n, k	Add Literal k to FSRn	1	11 0001 0nkk kkkk		
MOVIW	n mm	Move Indirect FSRn to W with pre/post inc/dec modifier, mm	1	00 0000 0001 0nmm	Z	**2, 3**
	k[n]	Move INDFn to W, Indexed Indirect.	1	11 1111 0nkk kkkk	Z	**2**
MOVWI	n mm	Move W to Indirect FSRn with pre/post inc/dec modifier, mm	1	00 0000 0001 1nmm		**2, 3**
	k[n]	Move W to INDFn, Indexed Indirect.	1	11 1111 1nkk kkkk		**2**

Note 1: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

2: If this instruction addresses an INDF register and the MSb of the corresponding FSR is set, this instruction will require one additional instruction cycle.

3: See Table in the MOVIW and MOVWI instruction descriptions.

FIGURE 30-3: POR AND POR REARM WITH SLOW RISING VDD



Note 1: When NPOR is low, the device is held in Reset.
2: TPOR 1 μs typical.
3: TVLOW 2.7 μs typical.

TABLE 30-9: CLKOUT AND I/O TIMING PARAMETERS

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS11	TosH2ckL	FOSC↑ to CLKOUT↓ (1)	—	—	70	ns	VDD = 3.3-5.0V
OS12	TosH2ckH	FOSC↑ to CLKOUT↑ (1)	—	—	72	ns	VDD = 3.3-5.0V
OS13	TckL2ioV	CLKOUT↓ to Port out valid(1)	—	—	20	ns	
OS14	TioV2ckH	Port input valid before CLKOUT↑(1)	TOSC + 200 ns	—	—	ns	
OS15	TosH2ioV	Fosc↑ (Q1 cycle) to Port out valid	—	50	70*	ns	VDD = 3.3-5.0V
OS16	TosH2ioI	Fosc↑ (Q2 cycle) to Port input invalid (I/O in hold time)	50	—	—	ns	VDD = 3.3-5.0V
OS17	TioV2osH	Port input valid to Fosc↑ (Q2 cycle) (I/O in setup time)	20	—	—	ns	
OS18*	TioR	Port output rise time	— —	40 15	72 32	ns	VDD = 1.8V VDD = 3.3-5.0V
OS19*	TioF	Port output fall time	— —	28 15	55 30	ns	VDD = 1.8V VDD = 3.3-5.0V
OS20*	Tinp	INT pin input high or low time	25	—	—	ns	
OS21*	Tioc	Interrupt-on-change new input level time	25	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4 x TOSC.

Note: Unless otherwise noted, VIN = 5V, FOSC = 300 kHz, CIN = 0.1 µF, TA = 25°C.

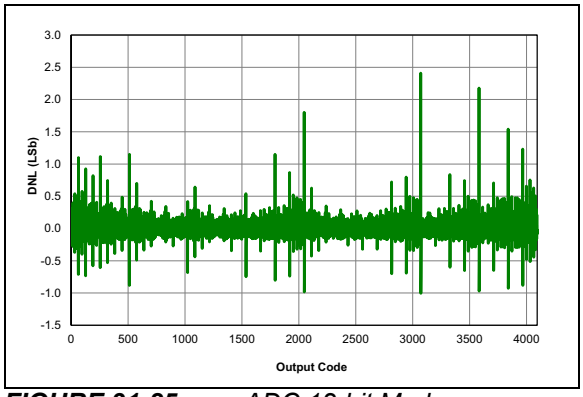


FIGURE 31-85: *ADC 12-bit Mode, Single-Ended DNL, VDD = 3.0V, TAD = 1 µS, 25°C.*

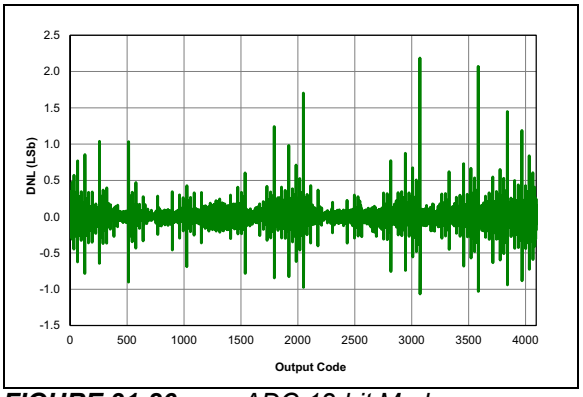


FIGURE 31-86: *ADC 12-bit Mode, Single-Ended DNL, VDD = 3.0V, TAD = 4 µS, 25°C.*

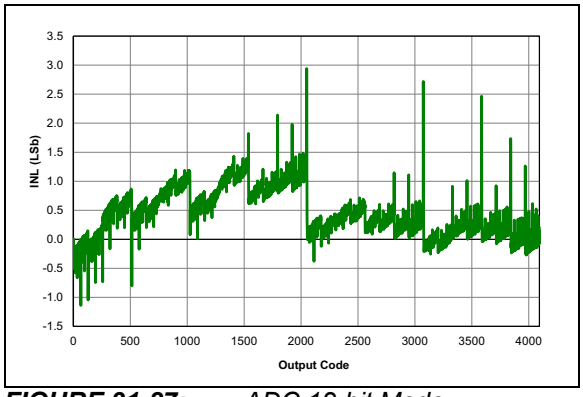


FIGURE 31-87: *ADC 12-bit Mode, Single-Ended INL, VDD = 3.0V, TAD = 1 µS, 25°C.*

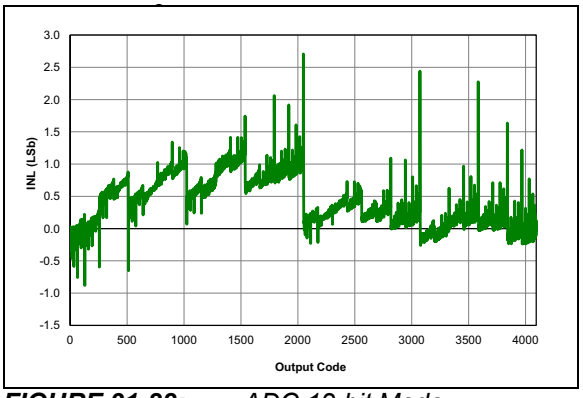


FIGURE 31-88: *ADC 12-bit Mode, Single-Ended INL, VDD = 3.0V, TAD = 4 µS, 25°C.*

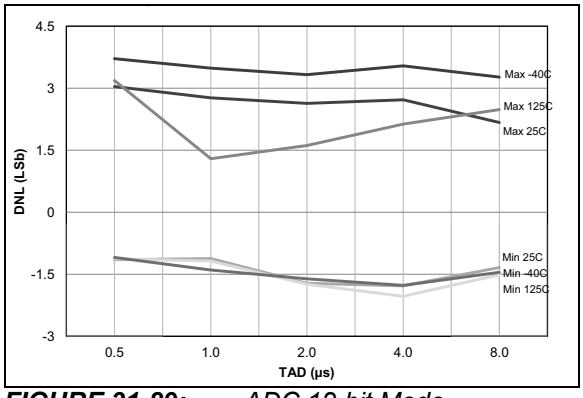


FIGURE 31-89: *ADC 12-bit Mode, Single-Ended DNL, VDD = 3.0V, VREF = 3.0V.*

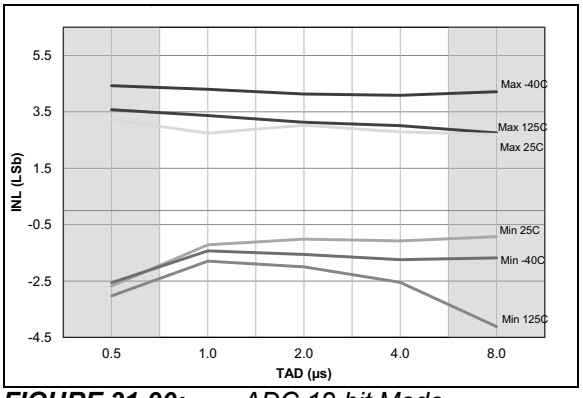


FIGURE 31-90: *ADC 12-bit Mode, Single-Ended INL, VDD = 3.0V, VREF = 3.0V.*

Note: Unless otherwise noted, VIN = 5V, FOSC = 300 kHz, CIN = 0.1 µF, TA = 25°C.

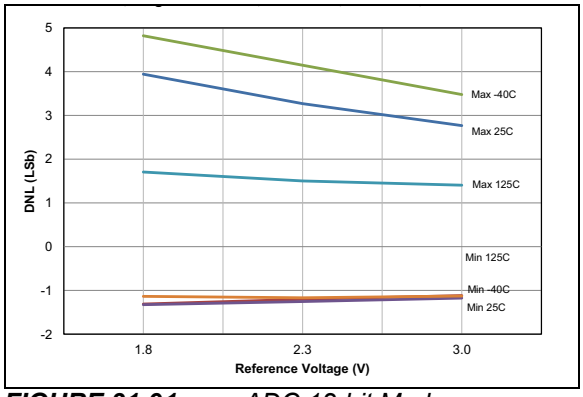


FIGURE 31-91: *ADC 12-bit Mode, Single-Ended DNL, VDD = 3.0V, TAD = 1 µS.*

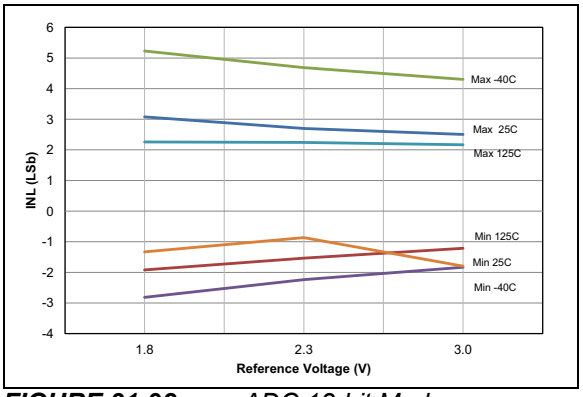


FIGURE 31-92: *ADC 12-bit Mode, Single-Ended INL, VDD = 3.0V, TAD = 1 µS.*

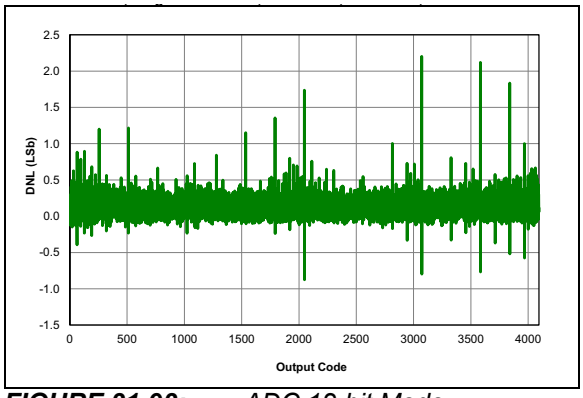


FIGURE 31-93: *ADC 12-bit Mode, Single-Ended DNL, VDD = 5.5V, TAD = 1 µS, 25°C.*

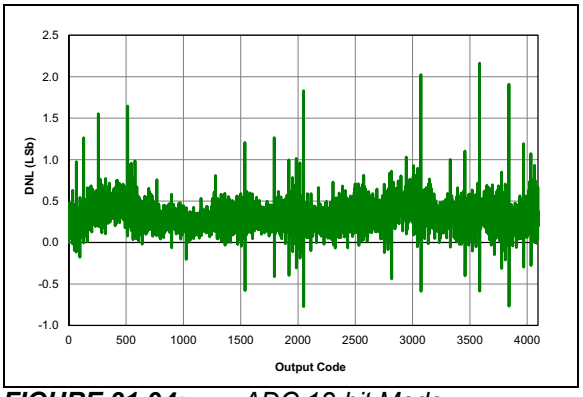


FIGURE 31-94: *ADC 12-bit Mode, Single-Ended DNL, VDD = 5.5V, TAD = 4 µS, 25°C.*

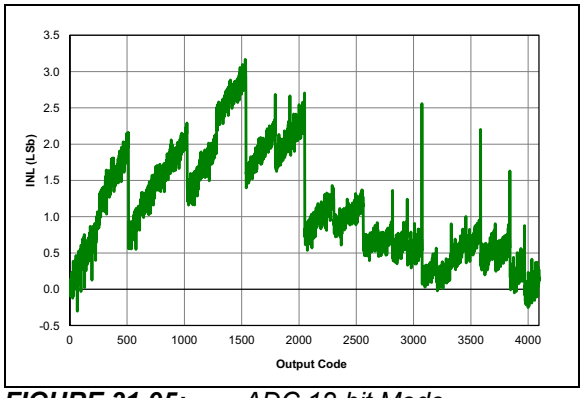


FIGURE 31-95: *ADC 12-bit Mode, Single-Ended INL, VDD = 5.5V, TAD = 1 µS, 25°C.*

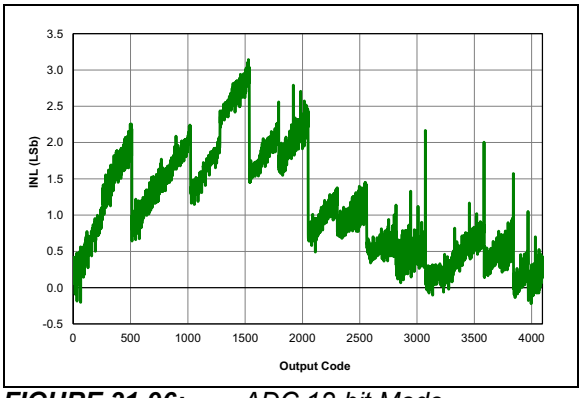
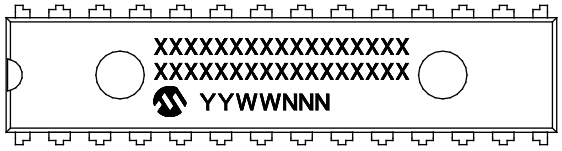


FIGURE 31-96: *ADC 12-bit Mode, Single-Ended INL, VDD = 5.5V, TAD = 4 µS, 25°C.*

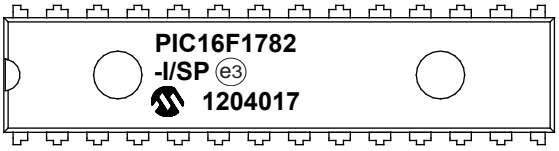
33.0 PACKAGING INFORMATION

33.1 Package Marking Information

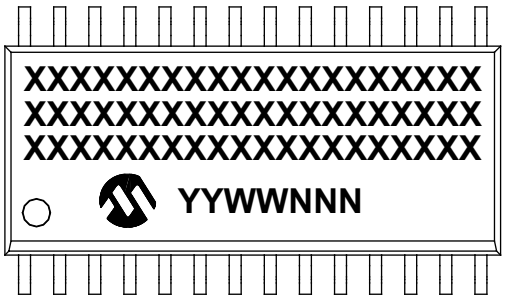
28-Lead SPDIP (.300")



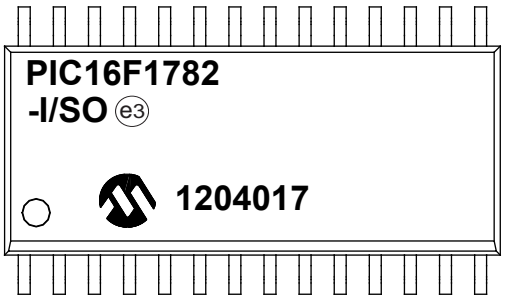
Example



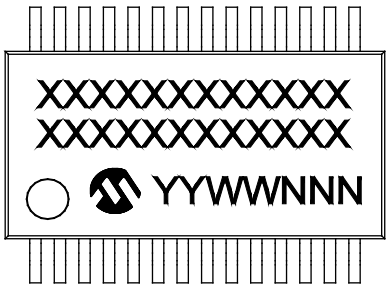
28-Lead SOIC (7.50 mm)



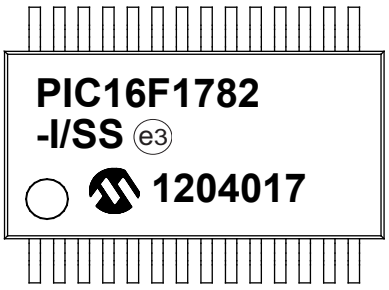
Example



28-Lead SSOP (5.30 mm)



Example

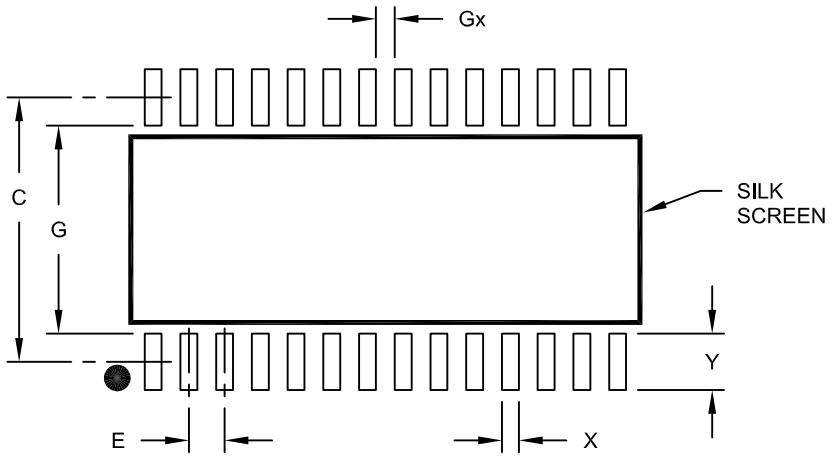


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A